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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

JUN 10 2005

Applicant : Sarah E. Kim et. al. Art Unit: 2814
 Serial No.: 10/659,044 Examiner: Thao X Le
 Filed : September 9, 2003 Assignee: Intel Corporation
 Title : THICK METAL LAYER INTEGRATED PROCESS FLOW TO IMPROVE
 POWER DELIVERY AND MECHANICAL BUFFERING

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 Commissioner for Patents
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AMENDMENT

Please enter.
 In response to the Office action mailed April 11, 2005,
 please amend the application as follows:

TL
 07/21/05 Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.

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